



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



# UltraTEC™ Series UT6,19,F1,4040

## Thermoelectric Module



The UltraTEC™ Series is a high heat pumping density thermoelectric module (TEM). The module is assembled with a large number of semiconductor couples to achieve a higher heat pumping capacity than standard single stage TEMs.

This product line is available in multiple configurations and is ideal for applications that require higher cooling capacities with limited surface area. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the UltraTEC™ Series is designed for higher current and larger heat-pumping applications.

### FEATURES AND BENEFITS

- High heat pump density
- Precise temperature control
- Reliable solid state operation
- No sound or vibration
- DC operation
- RoHS compliant

### APPLICATIONS

- Analytical instrumentation
- Clinical diagnostics
- Photonics laser systems
- Electronic enclosure cooling
- Food and beverage cooling
- Chillers (liquid cooling)

Americas: +1.919.597.7300

Europe: +46.31.420530

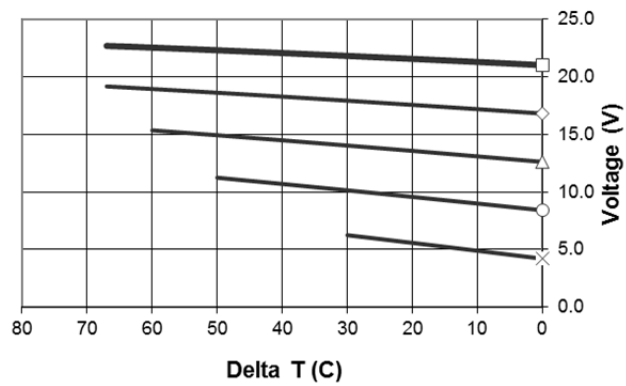
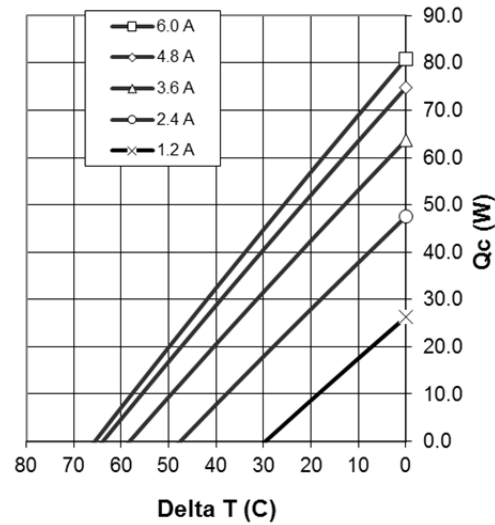
Asia: +86.755.2714.1166

ets.sales@lairdtech.com

[www.lairdtech.com](http://www.lairdtech.com)

# UltraTEC™ Series UT6,19,F1,4040

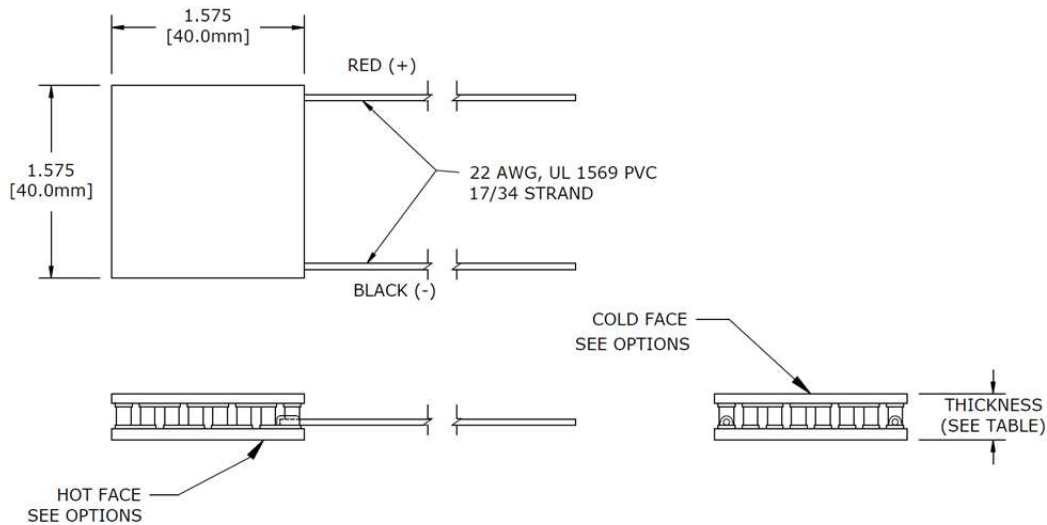
## Thermoelectric Module



### SPECIFICATIONS

TECHNICAL					
Hot Side Temperature	25°C	50°C			
Qmax	80.9 W	88.8 W			
Delta Tmax	67°C	75°C			
I <sub>max</sub> (A)	6.0	6.0			
V <sub>max</sub> (V)	22.6	25.6			
Module Resistance (ohms)	3.49	3.94			
Suffix	Thickness	Flatness & Parallelism	Hot Face	Cold Face	Lead Length
TA	0.150" ± 0.001"	0.001" / 0.001"	Lapped	Lapped	6.0"
TB	0.150" ± 0.0005"	0.0005" / 0.0005"	Lapped	Lapped	6.0"

### MECHANICAL DRAWING



### OPERATING TIPS

- Max operating temperature: 80°C
- Do not exceed  $I_{max}$  or  $V_{max}$  when operating module
- Reference assembly guidelines for installation

### THR- UltraTEC<sup>™</sup> Series UT6,19,F1,4040\_121815

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